

# 74HC4017; 74HCT4017

Johnson decade counter with 10 decoded outputs

Rev. 03 — 8 January 2008

Product data sheet

## 1. General description

---

The 74HC4017; 74HCT4017 is a high-speed Si-gate CMOS device and is pin compatible with the HEF4017.

The 74HC4017; 74HCT4017 is a 5-stage Johnson decade counter with 10 decoded active HIGH outputs (Q0 to Q9), an active LOW output from the most significant flip-flop ( $\overline{Q5-9}$ ), active HIGH and active LOW clock inputs (CP0 and  $\overline{CP1}$ ) and an overriding asynchronous master reset input (MR).

The counter is advanced by either a LOW-to-HIGH transition at CP0 while  $\overline{CP1}$  is LOW or a HIGH-to-LOW transition at  $\overline{CP1}$  while CP0 is HIGH (see [Table 3](#)).

When cascading counters, the  $\overline{Q5-9}$  output, which is LOW while the counter is in states 5, 6, 7, 8 and 9, can be used to drive the CP0 input of the next counter.

A HIGH on MR resets the counter to zero (Q0 =  $\overline{Q5-9}$  = HIGH; Q1 to Q9 = LOW) independent of the clock inputs (CP0 and  $\overline{CP1}$ ).

Automatic code correction of the counter is provided by an internal circuit: following any illegal code the counter returns to a proper counting mode within 11 clock pulses.

## 2. Features

---

- Multiple package options
- Complies with JEDEC standard no. 7 A
- ESD protection:
  - ◆ HBM JESD22-A114E exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
<b>74HC4017</b>				
74HC4017N	-40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HC4017D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HC4017DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HC4017PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HC4017BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal-enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
<b>74HCT4017</b>				
74HCT4017N	-40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT4017D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT4017BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal-enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1

### 4. Functional diagram

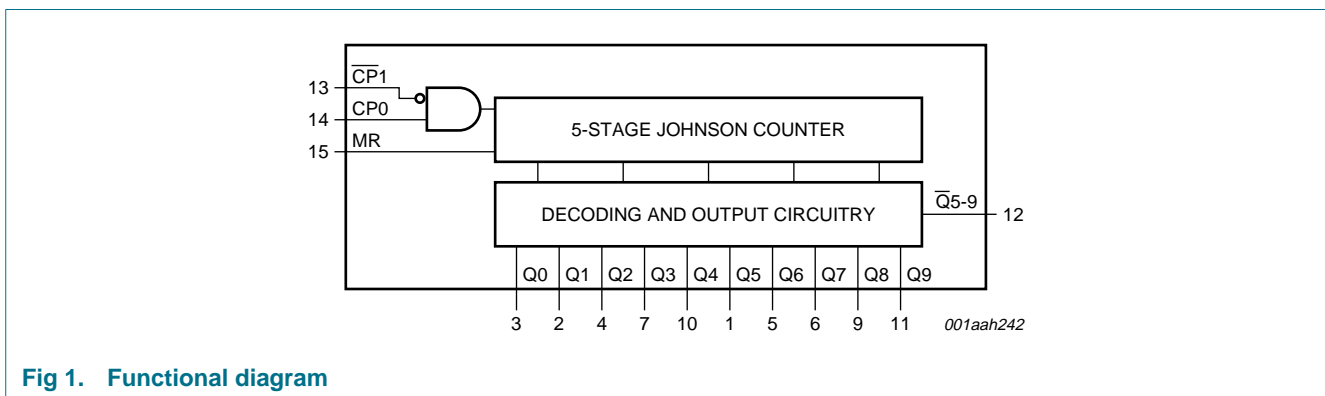


Fig 1. Functional diagram

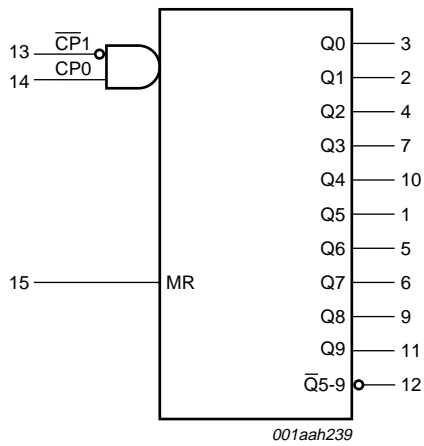


Fig 2. Logic symbol

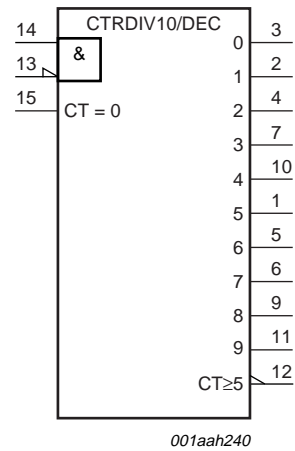


Fig 3. IEC logic symbol

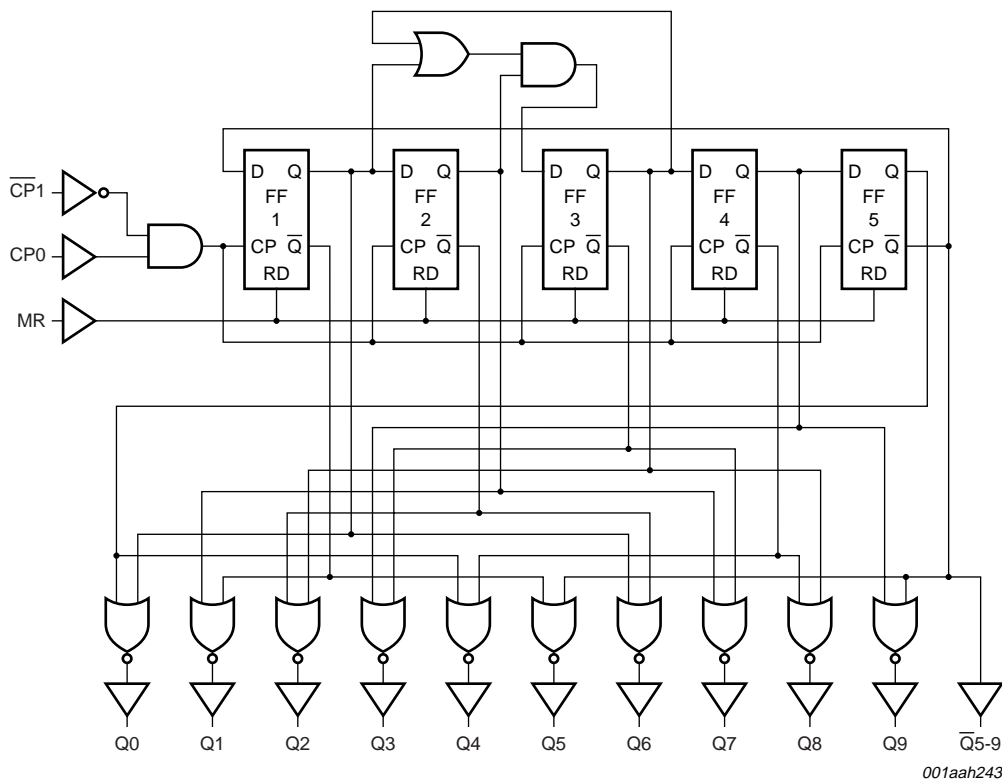
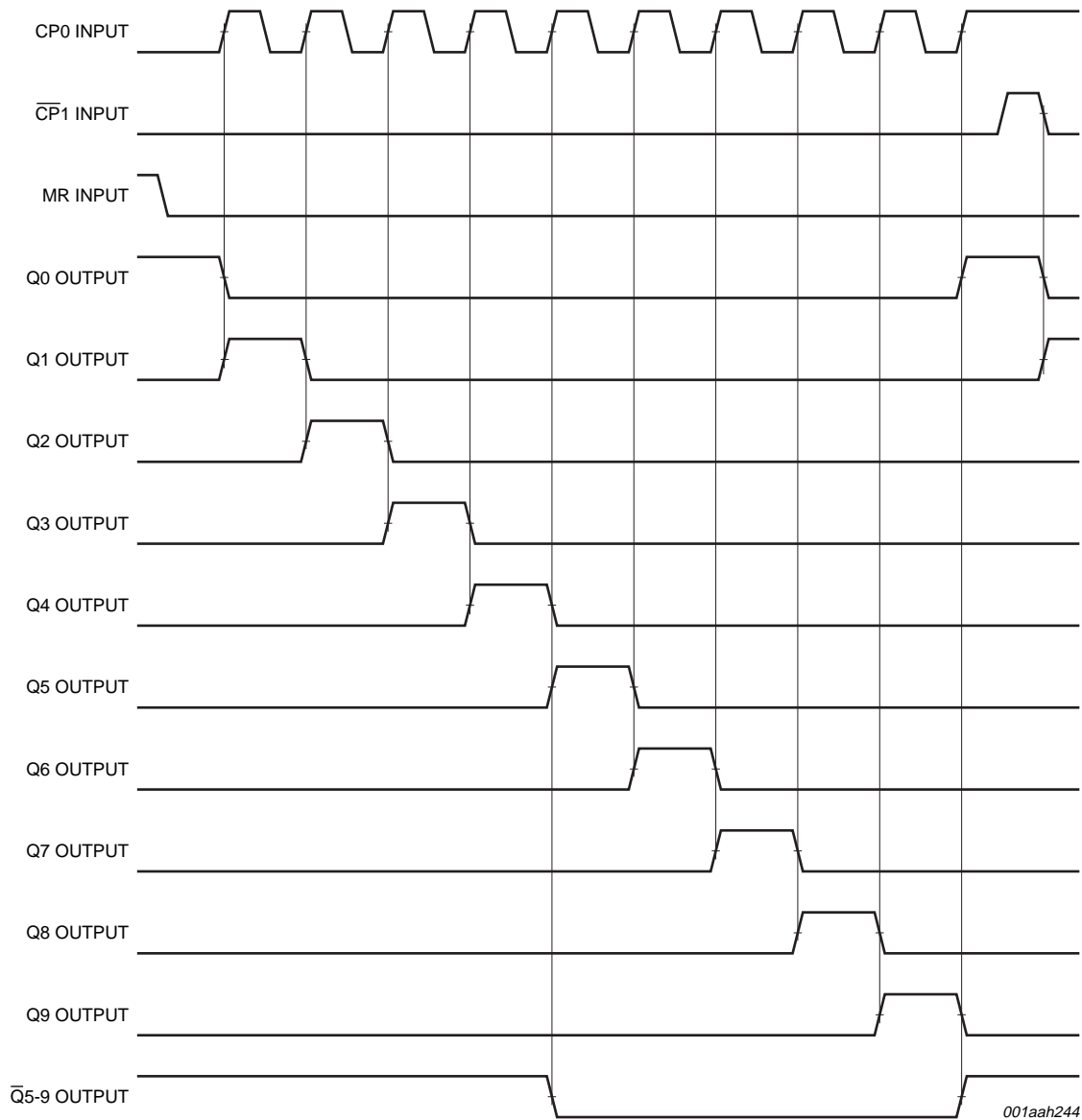


Fig 4. Logic diagram

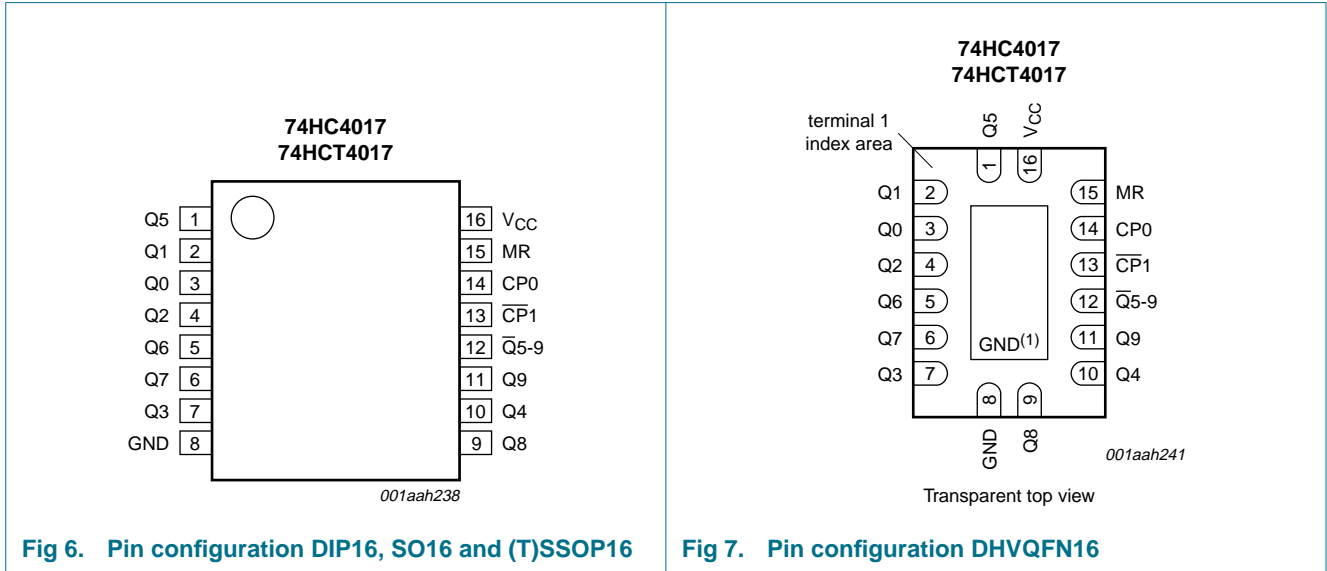


001aah244

Fig 5. Timing diagram

## 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

**Table 2. Pin description**

Symbol	Pin	Description
Q[0:9]	3, 2, 4, 7, 10, 1, 5, 6, 9, 11	decoded output
GND	8	ground (0 V)
$\overline{Q}5-9$	12	carry output (active LOW)
$\overline{CP}1$	13	clock input (HIGH-to-LOW edge-triggered)
CP0	14	clock input (LOW-to-HIGH edge-triggered)
MR	15	master reset input (active HIGH)
V <sub>CC</sub>	16	supply voltage

## 6. Functional description

**Table 3.** Function table<sup>[1]</sup>

MR	CP0	$\overline{CP1}$	Operation
H	X	X	Q0 = $\overline{Q5-9}$ = HIGH; Q1 to Q9 = LOW
L	H	↓	counter advances
L	↑	L	counter advances
L	L	X	no change
L	X	H	no change
L	H	↑	no change
L	↓	L	no change

- [1] H = HIGH voltage level;  
L = LOW voltage level;  
X = don't care;  
↑ = LOW-to-HIGH transition;  
↓ = HIGH-to-LOW transition;

## 7. Limiting values

**Table 4.** Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	[1] -	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	[1] -	±20	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±25	mA
I <sub>CC</sub>	supply current		-	50	mA
I <sub>GND</sub>	ground current		-50	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C			
	DIP16 package		[2] -	750	mW
	SO16 package		[3] -	500	mW
	(T)SSOP16 package		[4] -	500	mW
	DHVQFN16 package		[5] -	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
[2] P<sub>tot</sub> derates linearly with 12 mW/K above 70 °C.  
[3] P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.  
[4] P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.  
[5] P<sub>tot</sub> derates linearly with 4.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>74HC4017</b>						
$V_{CC}$	supply voltage		2.0	5.0	6.0	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	ns/V
$T_{amb}$	ambient temperature		-40	-	+125	°C
<b>74HCT4017</b>						
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns/V
$T_{amb}$	ambient temperature		-40	-	+125	°C

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4017</b>										
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	1.2	-	1.5	-	1.5	-	V
		$V_{CC} = 4.5\text{ V}$	3.15	2.4	-	3.15	-	3.15	-	V
		$V_{CC} = 6.0\text{ V}$	4.2	3.2	-	4.2	-	4.2	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	0.8	0.5	-	0.5	-	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	2.1	1.35	-	1.35	-	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	2.8	1.8	-	1.8	-	1.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -20\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20\ \mu\text{A}; V_{CC} = 6.0\text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	4.32	-	3.84	-	3.7	-	V
	$I_O = -5.2\text{ mA}; V_{CC} = 6.0\text{ V}$	5.48	5.81	-	5.34	-	5.2	-	V	

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
<b>74HCT4017</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 0 A	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A								
		CP0 input	-	25	90	-	113	-	123	μA
		CP1 input	-	40	144	-	180	-	196	μA
		MR input	-	50	180	-	225	-	245	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF



10. Dynamic characteristics

**Table 7. Dynamic characteristics**  
*GND = 0 V;  $t_r = t_f = 6 \text{ ns}$ ;  $C_L = 50 \text{ pF}$ ; see [Figure 11](#).*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit	
			Min	Typ	Max	Min	Max	Min	Max		
<b>74HC4017</b>											
$t_{pd}$	propagation delay	CP0 to Qn; CP0 to $\overline{Q}5-9$ ; see <a href="#">Figure 10</a>	<a href="#">[1]</a>								
		$V_{CC} = 2.0 \text{ V}$	-	63	230	-	290	-	345	ns	
		$V_{CC} = 4.5 \text{ V}$	-	23	46	-	58	-	69	ns	
		$V_{CC} = 5.0 \text{ V}$ ; $C_L = 15 \text{ pF}$	-	20	-	-	-	-	-	ns	
		$V_{CC} = 6.0 \text{ V}$	-	18	39	-	49	-	59	ns	
		$\overline{CP}1$ to Qn; $\overline{CP}1$ to $\overline{Q}5-9$ ; see <a href="#">Figure 10</a>									
		$V_{CC} = 2.0 \text{ V}$	-	61	250	-	315	-	375	ns	
		$V_{CC} = 4.5 \text{ V}$	-	22	50	-	63	-	75	ns	
$t_{PHL}$	HIGH to LOW propagation delay	$V_{CC} = 5.0 \text{ V}$ ; $C_L = 15 \text{ pF}$	-	20	-	-	-	-	ns		
		$V_{CC} = 6.0 \text{ V}$	-	18	43	-	54	-	64	ns	
		MR to Q[1:9]; see <a href="#">Figure 10</a>									
		$V_{CC} = 2.0 \text{ V}$	-	52	230	-	290	-	345	ns	
$t_{PLH}$	LOW to HIGH propagation delay	$V_{CC} = 4.5 \text{ V}$	-	19	46	-	58	-	69	ns	
		$V_{CC} = 6.0 \text{ V}$	-	15	39	-	49	-	59	ns	
		MR to $\overline{Q}5-9$ , Q0; see <a href="#">Figure 10</a>									
$t_t$	transition time	$V_{CC} = 2.0 \text{ V}$	-	55	230	-	290	-	345	ns	
		$V_{CC} = 4.5 \text{ V}$	-	20	46	-	58	-	69	ns	
		$V_{CC} = 6.0 \text{ V}$	-	16	39	-	49	-	59	ns	
$t_f$	transition time	see <a href="#">Figure 10</a>	<a href="#">[2]</a>								
		$V_{CC} = 2.0 \text{ V}$	-	19	75	-	95	-	110	ns	
		$V_{CC} = 4.5 \text{ V}$	-	7	15	-	19	-	22	ns	
$t_w$	pulse width	$V_{CC} = 6.0 \text{ V}$	-	6	13	-	16	-	19	ns	
		CP0 and $\overline{CP}1$ (HIGH or LOW); see <a href="#">Figure 9</a>									
		$V_{CC} = 2.0 \text{ V}$	80	17	-	100	-	120	-	ns	
$t_w$	pulse width	$V_{CC} = 4.5 \text{ V}$	16	6	-	20	-	24	-	ns	
		$V_{CC} = 6.0 \text{ V}$	14	5	-	17	-	20	-	ns	
		MR (HIGH); see <a href="#">Figure 9</a>									
$t_w$	pulse width	$V_{CC} = 2.0 \text{ V}$	80	19	-	100	-	120	-	ns	
		$V_{CC} = 4.5 \text{ V}$	16	7	-	20	-	24	-	ns	
		$V_{CC} = 6.0 \text{ V}$	14	6	-	17	-	20	-	ns	

**Table 7. Dynamic characteristics ...continued**  
*GND = 0 V;  $t_r = t_f = 6$  ns;  $C_L = 50$  pF; see [Figure 11](#).*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{su}$	set-up time	$\overline{CP1}$ to CP0; CP0 to $\overline{CP1}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V	50	-8	-	65	-	75	-	ns
		$V_{CC} = 4.5$ V	10	-3	-	13	-	15	-	ns
		$V_{CC} = 6.0$ V	9	-2	-	11	-	13	-	ns
$t_h$	hold time	$\overline{CP1}$ to CP0; CP0 to $\overline{CP1}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0$ V	50	17	-	65	-	75	-	ns
		$V_{CC} = 4.5$ V	10	6	-	13	-	15	-	ns
		$V_{CC} = 6.0$ V	9	5	-	11	-	13	-	ns
$t_{rec}$	recovery time	MR to CP0 and MR to $\overline{CP1}$ ; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	5	-17	-	5	-	5	-	ns
		$V_{CC} = 4.5$ V	5	-6	-	5	-	5	-	ns
		$V_{CC} = 6.0$ V	5	-5	-	5	-	5	-	ns
$f_{max}$	maximum frequency	CP0 or $\overline{CP1}$ ; see <a href="#">Figure 9</a>								
		$V_{CC} = 2.0$ V	6.0	23	-	4.8	-	4.0	-	MHz
		$V_{CC} = 4.5$ V	30	70	-	24	-	20	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	77	-	-	-	-	-	MHz
		$V_{CC} = 6.0$ V	25	83	-	28	-	24	-	MHz
$C_{PD}$	power dissipation capacitance	$V_I = GND$ to $V_{CC}$ ; $V_{CC} = 5$ V; $f_i = 1$ MHz	[3]	-	35	-	-	-	-	pF
<b>74HCT4017</b>										
$t_{pd}$	propagation delay	CP0 to Qn; CP0 to $\overline{Q5-9}$ ; see <a href="#">Figure 10</a>								
		$V_{CC} = 4.5$ V	-	25	46	-	58	-	69	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	21	-	-	-	-	-	ns
		$\overline{CP1}$ to Qn; $\overline{CP1}$ to $\overline{Q5-9}$ ; see <a href="#">Figure 10</a>								
		$V_{CC} = 4.5$ V	-	25	50	-	63	-	75	ns
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	21	-	-	-	-	-	ns
$t_{PHL}$	HIGH to LOW propagation delay	MR to Q[1:9]; see <a href="#">Figure 10</a>								
		$V_{CC} = 4.5$ V	-	22	46	-	58	-	69	ns
$t_{PLH}$	LOW to HIGH propagation delay	MR to $\overline{Q5-9}$ , Q0; see <a href="#">Figure 10</a>								
		$V_{CC} = 4.5$ V	-	20	46	-	58	-	69	ns

**Table 7. Dynamic characteristics ...continued**  
*GND = 0 V;  $t_r = t_f = 6$  ns;  $C_L = 50$  pF; see [Figure 11](#).*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_t$	transition time	see <a href="#">Figure 10</a> <a href="#">[2]</a>								
		$V_{CC} = 4.5$ V	-	7	15	-	19	-	22	ns
$t_W$	pulse width	CP0 and $\overline{CP1}$ (HIGH or LOW); see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V	16	7	-	20	-	24	-	ns
		MR (HIGH); see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V	16	4	-	20	-	24	-	ns
$t_{su}$	set-up time	$\overline{CP1}$ to CP0; CP0 to $\overline{CP1}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V	10	-3	-	13	-	15	-	ns
$t_h$	hold time	$\overline{CP1}$ to CP0; CP0 to $\overline{CP1}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 4.5$ V	10	6	-	13	-	15	-	ns
$t_{rec}$	recovery time	MR to CP0 and MR to $\overline{CP1}$ ; see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V	5	-5	-	5	-	5	-	ns
$f_{max}$	maximum frequency	CP0 or $\overline{CP1}$ ; see <a href="#">Figure 9</a>								
		$V_{CC} = 4.5$ V	30	61	-	24	-	20	-	MHz
		$V_{CC} = 5.0$ V; $C_L = 15$ pF	-	67	-	-	-	-	-	MHz
$C_{PD}$	power dissipation capacitance	$V_I = GND$ to $V_{CC} - 1.5$ V; <a href="#">[3]</a> $V_{CC} = 5$ V; $f_i = 1$ MHz	-	36	-	-	-	-	-	pF

[1]  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .

[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .

[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W):

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

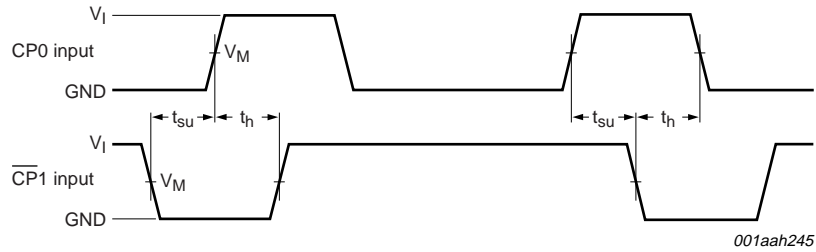
$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in V;

$N$  = number of inputs switching;

$\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

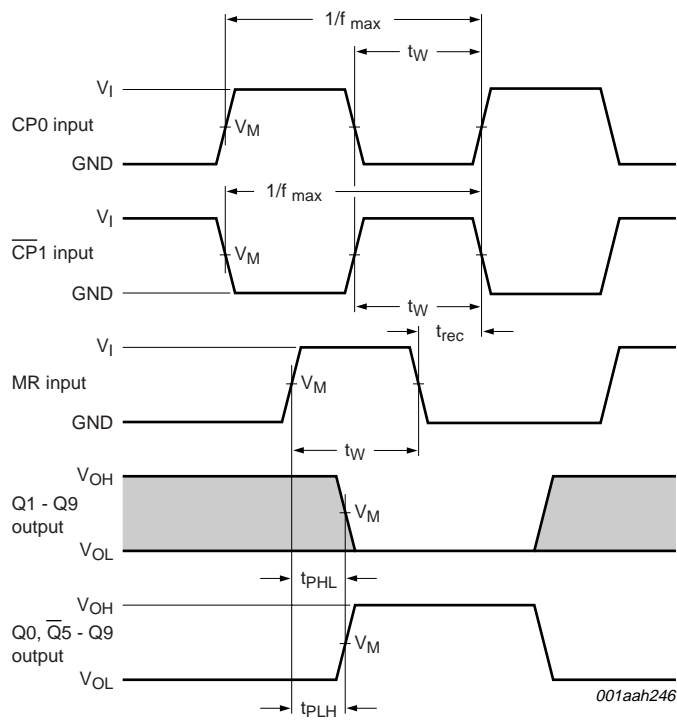
11. Waveforms



Measurement points are given in Table 8.

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

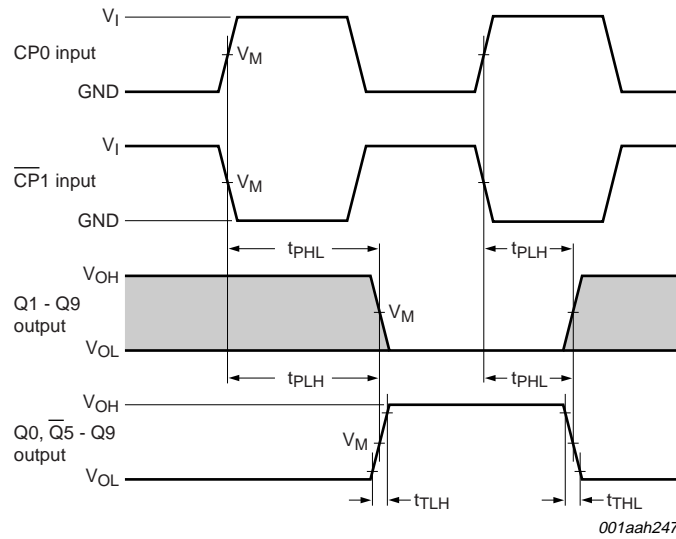
Fig 8. Waveforms showing the set-up and hold times for CP0 to CP1 and CP1 to CP0



Measurement points are given in Table 8.

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig 9. Waveforms showing the minimum pulse width for CP0, CP1 and MR input; the maximum frequency for CP0 and CP1 input; the recovery time for MR and the MR input to Qn and Q5-9 output propagation delays



Measurement points are given in [Table 8](#).

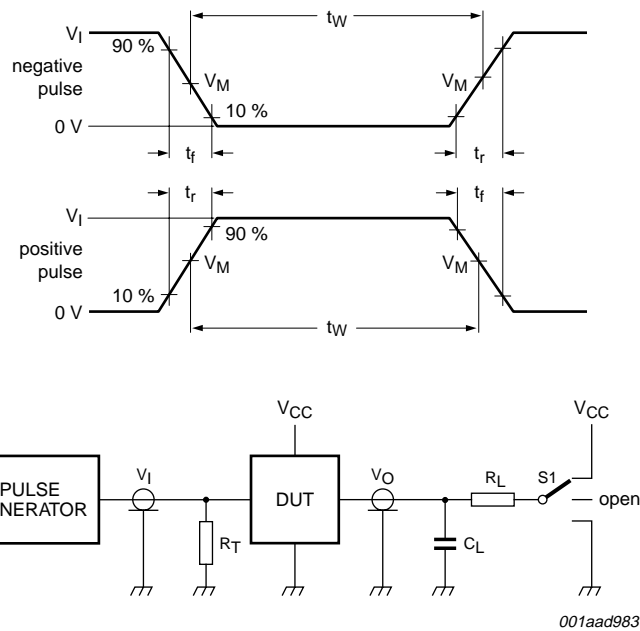
$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Conditions:  $\overline{CP1} = \text{LOW}$  while CP0 is triggered on a LOW-to-HIGH transition and CP0 = HIGH, while  $\overline{CP1}$  is triggered on a HIGH-to-LOW transition.

**Fig 10. Waveforms showing the propagation delays for CP0, CP1 to Qn, Q5-9 outputs and the output transition times**

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC4017	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74HCT4017	1.3 V	1.3 V



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

Fig 11. Load circuitry for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC4017	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT4017	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

## 12. Application information

Some examples of applications for the 74HC4017; 74HCT4017 are:

- Decade counter with decimal decoding
- 1 out of n decoding counter (when cascaded)
- Sequential controller
- Timer

Figure 12 shows a technique for extending the number of decoded output states for the 74HC4017; 74HCT4017. Decoded outputs are sequential within each stage and from stage to stage, with no dead time (except propagation delay).

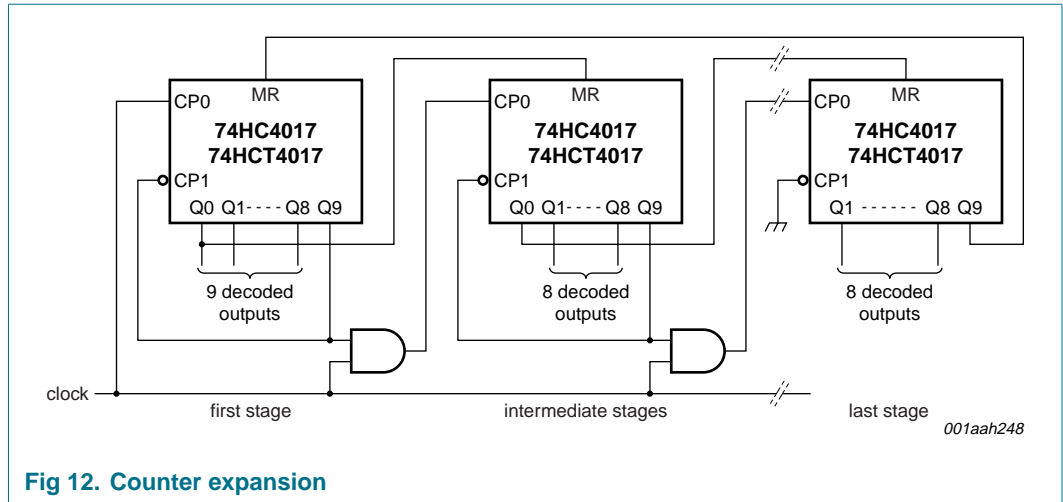


Fig 12. Counter expansion

**Remark:** It is essential not to enable the counter on  $\overline{CP1}$  when  $CP0$  is HIGH, or on  $CP0$  when  $CP1$  is LOW, as this would cause an extra count.

Figure 13 shows an example of a divide-by 2 through divide-by 10 circuit using one 74HC4017; 74HCT4017. Since the 74HC4017; 74HCT4017 has an asynchronous reset, the output pulse widths are narrow (minimum expected pulse width is 6 ns). The output pulse widths can be enlarged by inserting an RC network at the MR input.

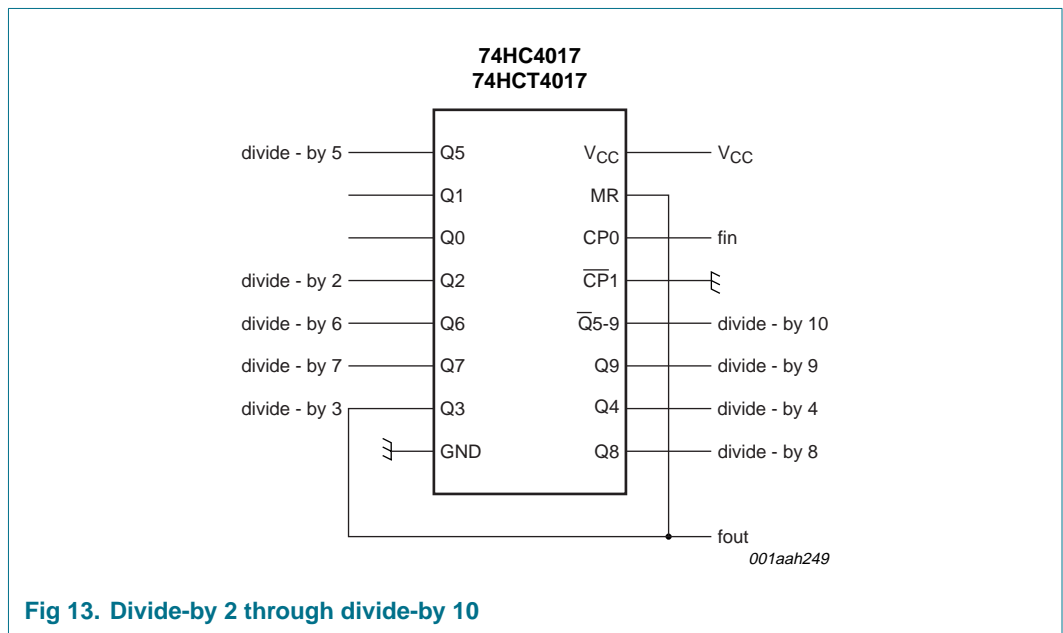


Fig 13. Divide-by 2 through divide-by 10

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

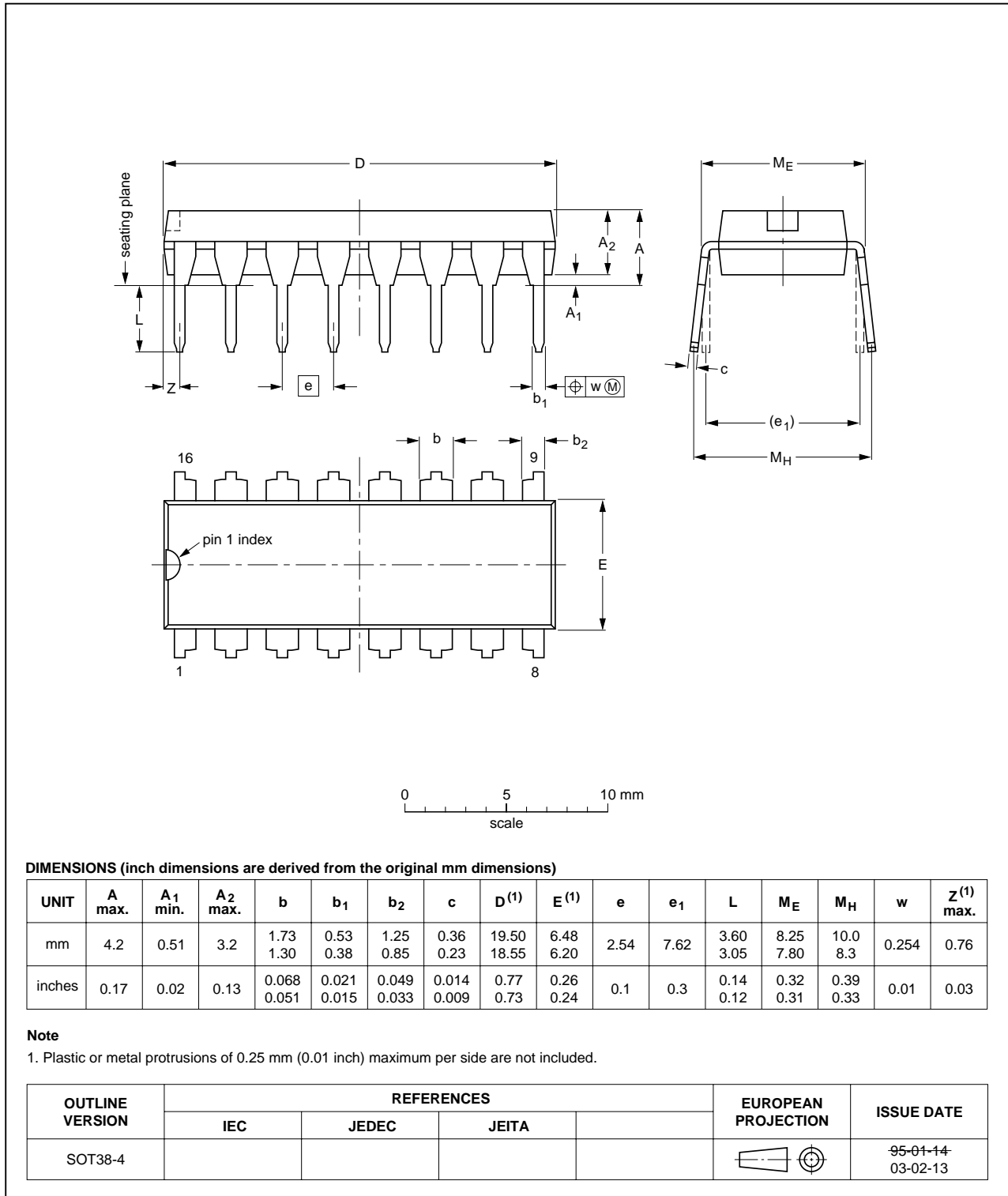


Fig 14. Package outline SOT38-4 (DIP16)



SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

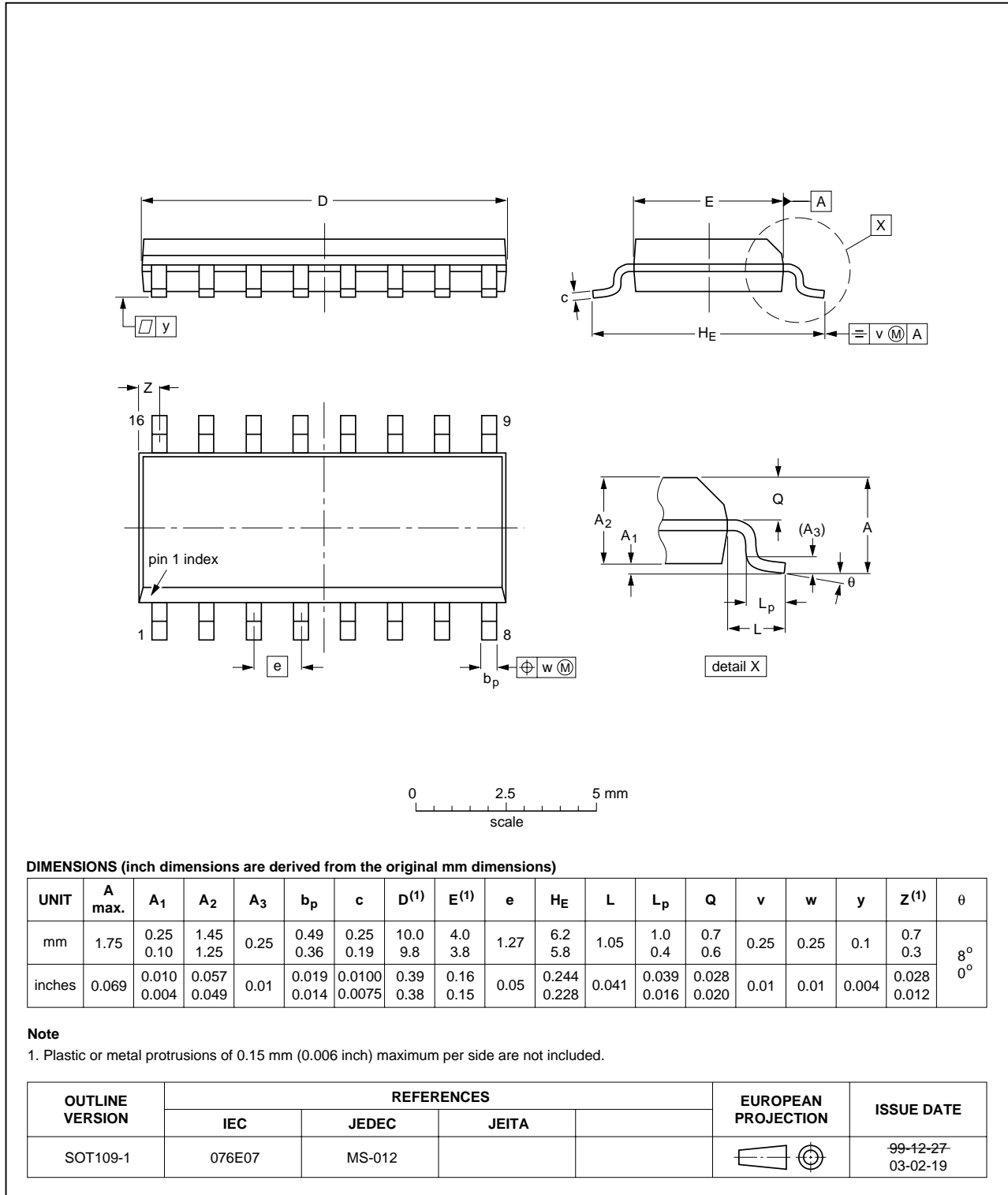


Fig 15. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

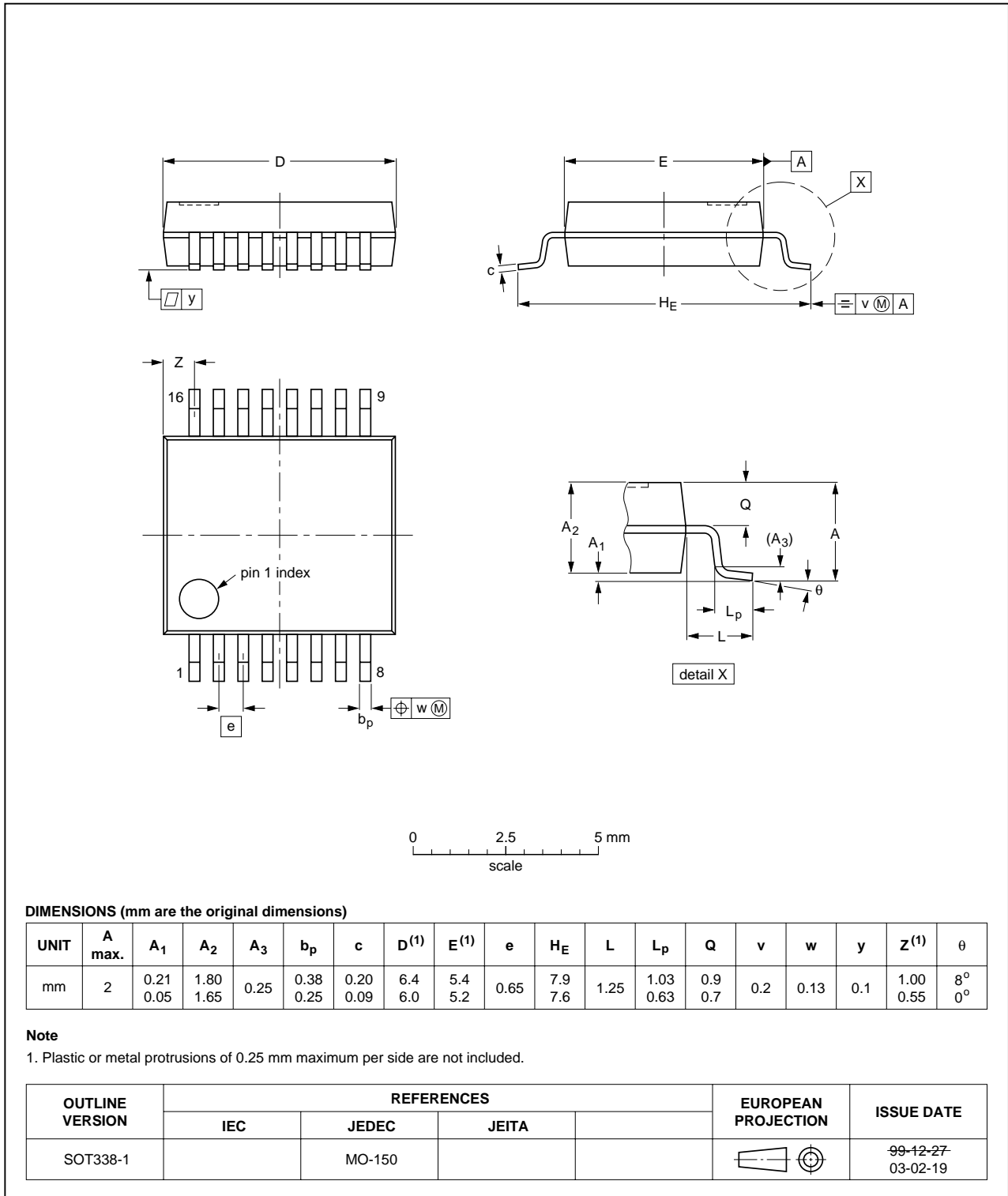


Fig 16. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1



Fig 17. Package outline SOT403-1 (TSSOP16)

DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm

SOT763-1

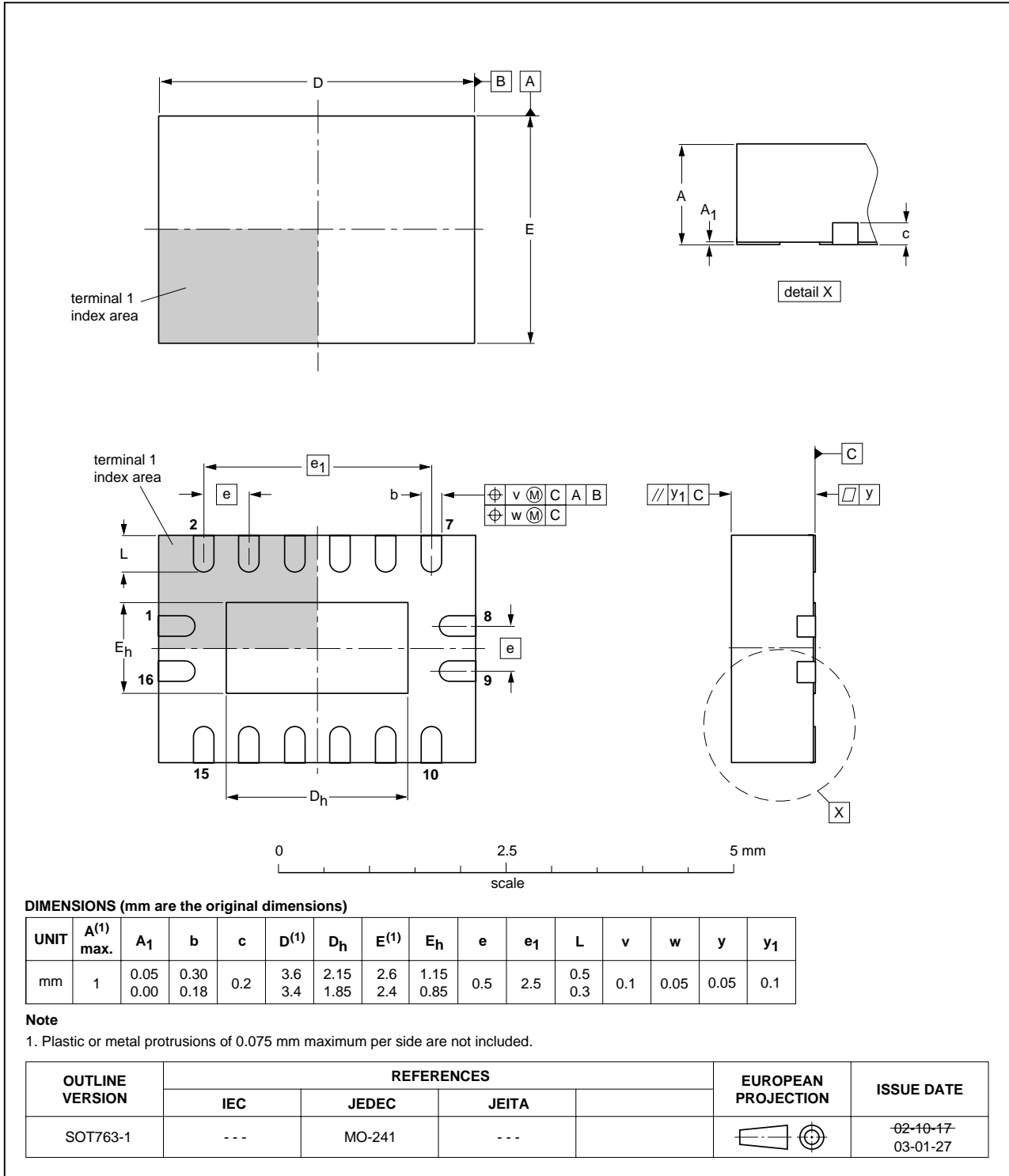


Fig 18. Package outline SOT763-1 (DHVQFN16)

## 14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4017_3	20080108	Product data sheet	-	74HC_HCT4017_CNV_2
Modifications:	<ul style="list-style-type: none"> <li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• <a href="#">Section 3</a>: DHVQFN16 package added.</li> <li>• <a href="#">Section 7</a>: derating values added for DHVQFN16 package.</li> <li>• <a href="#">Section 13</a>: outline drawing added for DHVQFN16 package.</li> </ul>			
74HC_HCT4017_CNV_2	19970829	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 16.2 Definitions

**Draft** — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

**Short data sheet** — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

### 16.3 Disclaimers

**General** — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

**Right to make changes** — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

**Suitability for use** — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or

malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

**Applications** — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Terms and conditions of sale** — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

**No offer to sell or license** — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

### 16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

## 17. Contact information

For additional information, please visit: <http://www.nxp.com>

For sales office addresses, send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

## 18. Contents

<b>1</b>	<b>General description</b> .....	<b>1</b>
<b>2</b>	<b>Features</b> .....	<b>1</b>
<b>3</b>	<b>Ordering information</b> .....	<b>2</b>
<b>4</b>	<b>Functional diagram</b> .....	<b>2</b>
<b>5</b>	<b>Pinning information</b> .....	<b>5</b>
5.1	Pinning .....	5
5.2	Pin description .....	5
<b>6</b>	<b>Functional description</b> .....	<b>6</b>
<b>7</b>	<b>Limiting values</b> .....	<b>6</b>
<b>8</b>	<b>Recommended operating conditions</b> .....	<b>7</b>
<b>9</b>	<b>Static characteristics</b> .....	<b>7</b>
<b>10</b>	<b>Dynamic characteristics</b> .....	<b>9</b>
<b>11</b>	<b>Waveforms</b> .....	<b>12</b>
<b>12</b>	<b>Application information</b> .....	<b>14</b>
<b>13</b>	<b>Package outline</b> .....	<b>16</b>
<b>14</b>	<b>Abbreviations</b> .....	<b>21</b>
<b>15</b>	<b>Revision history</b> .....	<b>21</b>
<b>16</b>	<b>Legal information</b> .....	<b>22</b>
16.1	Data sheet status .....	22
16.2	Definitions .....	22
16.3	Disclaimers .....	22
16.4	Trademarks .....	22
<b>17</b>	<b>Contact information</b> .....	<b>22</b>
<b>18</b>	<b>Contents</b> .....	<b>23</b>

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.



© NXP B.V. 2008.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

Date of release: 8 January 2008

Document identifier: 74HC\_HCT4017\_3

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9